

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A conductive composition which is used for a conductor of ~~an~~ a multilayer electronic component, comprising a metal particle and a metal oxide particle,

wherein said metal oxide particle ~~which~~ has an average particle size of 5 to 60 nm and a melting point of 1500°C or higher, and

wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the amount of the metal particle.

2. (Original) A conductive composition according to claim 1, further comprising a binder resin and a solvent dissolving the binder resin.

3. (Original) A conductive composition according to claim 1, wherein the average particle size of the metal oxide particle is 1/3 to 1/80 of that of the metal particle.

4. (Currently Amended) A conductive composition which is used for a conductor of ~~an~~ a multilayer electronic component comprising a metal particle and a metal oxide particle which has a BET value of 20 to 200 m²/g and a melting point of 1500°C or higher,

wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the amount of the metal particle.

5. (Original) A conductive composition according to claim 4, further comprising a binder resin and a solvent dissolving the binder resin.

6. (Original) A conductive composition according to claim 4, wherein the BET value of the metal oxide particle is 5 to 200 times that of the metal particle.

7. (Canceled)

8. (Currently Amended) ~~A ceramic electronic component according to claim 7,~~
ceramic electronic component comprising:

a ceramic substrate;

a conductive layer which is formed in at least one of the inside and outside of
the ceramic substrate and comprises a metal particle and a metal oxide particle,

wherein said metal oxide particle which has an average particle size of 5 to 60
nm and a melting point of 1500°C or higher, and

wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the
amount of the metal particle; and

which comprises a capacitor formed by including the ceramic substrate and the
conductive layer, wherein, in the conductive layer, the metal particle is at least one kind
selected from nickel and nickel alloys, and the metal oxide particle is an oxide compound
comprising at least one kind of metals selected from magnesium, aluminum, titanium and
zirconium.

9. (Currently Amended) ~~A ceramic electronic component according to claim 7,~~
A ceramic electronic component comprising:

a ceramic substrate;

a conductive layer which is formed in at least one of the inside and outside of
the ceramic substrate and comprises a metal particle and a metal oxide particle,

wherein said metal oxide particle which has an average particle size of 5 to 60
nm and a melting point of 1500°C or higher, and

wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the
amount of the metal particle; and

which comprises an insulator formed by including the ceramic substrate and
the conductive layer, wherein, in the conductive layer, the metal particle is at least one kind

selected from silver and silver alloys, and the metal oxide particle is an oxide compound comprising at least one kind of metals selected from magnesium, aluminum, titanium and zirconium.

10. (New) A conductive composition which is used for a conductor of an electronic component, comprising a metal particle and a metal oxide particle,
- wherein said metal oxide particle which has an average particle size of 5 to 60 nm and a melting point of 1500°C or higher, and
- wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the amount of the metal particle, and
- wherein the metal oxide particle is an oxide compound comprising at least one kind of metals selected from magnesium, aluminum, titanium, and zirconium.

11. (New) A conductive composition which is used for a conductor of an electronic component comprising a metal particle and a metal oxide particle which has a BET value of 20 to 200 m²/g and a melting point of 1500°C or higher,
- wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the amount of the metal particle, and
- wherein the metal oxide particle is an oxide compound comprising at least one kind of metals selected from magnesium, aluminum, titanium, and zirconium.